

E-Box with optional bondforce calibration

E-Box for wire bonders

The E-Box of the Hesse GmbH is a patent-registered visualisation system for control supported, reproducible adjustments of bondhead elements. It includes a camera for optical displaying of wedge, cutter and wire guide as well as a graphical support for adjustment- and positioning control. E-Box allows significant time reduction for setting up the machine.

E-Box

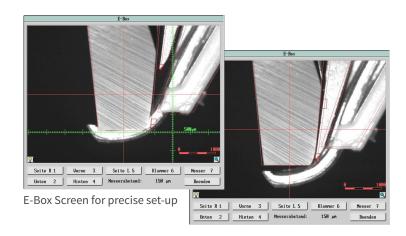
Adjustment tool for wire bonders

Advantages during Production

- Better reproducibility of the adjustment depending attributes (e.g. loop forming) after change of wearing parts
- Longer life time of wearing parts

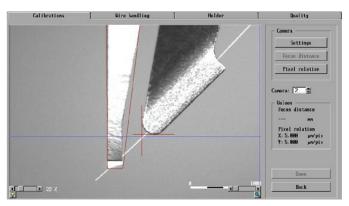
Advantages for Bond Process

- System for reproducible set-up of wedge, cutter and wire guide
- Camera system for optical visualisation of wedge, cutter and wire guide
- Set-up without microscope
- Free programmable, specified positions for bondhead elements
 - shown as limitation line
 - different views selectable (different sides, bottom, front etc.)
- Minimizes time expenditure for set-up work, set-up control and readjustment
- Process secured adjustment of wire feed elements (wedge, wire clamp, wire guide, cutter etc.)
- Graphical supported, visual control of:
 - wedge and wire guide position
 - distance between wedge and wire clamp
 - gap of wire clamp (fine wire)
 - wire pass
 - cutter respectively cutting position (heavy wire)



E-Box

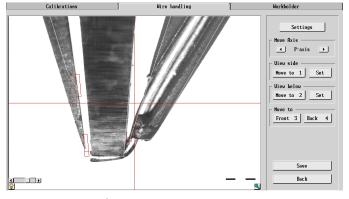
Adjustment tool for wire bonders



E-Box BJ820



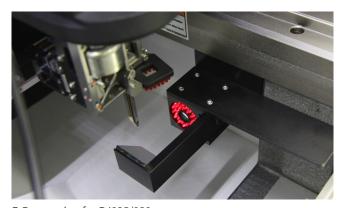
E-Box BJ830: graphical ball inspection



E-Box screen BJ935/939

E-Box version for BJ820

E-Box version for BJ830 with optional bondforce calibration



E-Box version for BJ935/939

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